

METHOD AND APPARATUS FOR COMBINING
MULTIPLE INTEGRATED CIRCUITS

ABSTRACT OF THE DISCLOSURE

An apparatus includes a circuit having first, second and third circuit portions, the first and third circuit portions each including at least one semiconductor circuit component. The second circuit portion includes
5 at least one non-semiconductor circuit component, and is free of semiconductor circuit components. A first substrate has the first and second circuit portions disposed adjacent one side thereof. A second substrate
10 is physically separate from the first substrate, and has the third circuit portion disposed adjacent a side thereof which faces the one side of the first substrate. The second and third circuit portions have electrically conductive parts which are coupled by thermo-formed
15 bonds.